

Exceptional service in the national interest



Residual Internal Stress Optimization for Thermoset Resin using Fiber Bragg Grating Sensors

Garth D. Rohr, Amy K. Kaczmarowski, Mark Stavig, Cory Gibson,
R. Allen Roach, Rex Jaramillo, Roger D. Rasberry

Sandia National Laboratories

Eric Udd

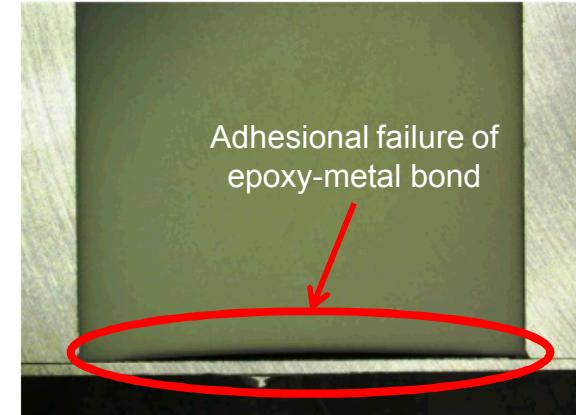
Columbia Gorge Research LLC



Sandia National Laboratories is a multi-program laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000. SAND2011-0439P

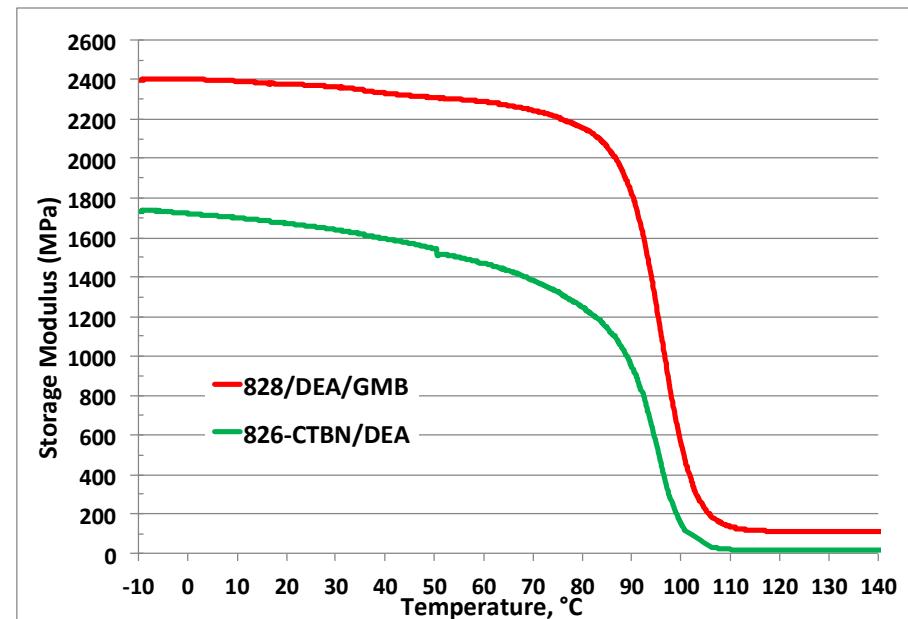
Epoxy Resins and their Stresses

- Epoxy resins provide protection for sensitive electronics
 - High voltage, shock, humidity, thermal environments
 - Mechanical and electrical properties of an epoxy system are key to success of component
 - These properties depend on the extent of cure of the epoxy
- Epoxy resins are often cured at elevated temperatures in order to speed reaction mechanisms that allow network formation
 - Stresses can develop as a result of cure that can result in adhesional or cohesive failures of the epoxy and ultimately the electronic components
- **Goal is to understand the development of these stresses in our system and minimize their impact**



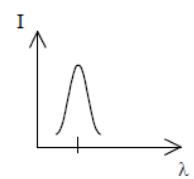
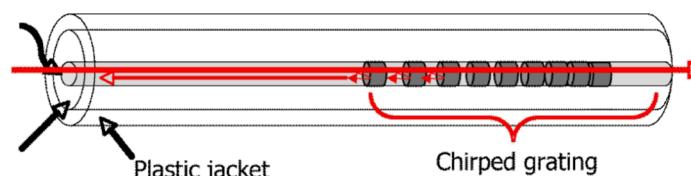
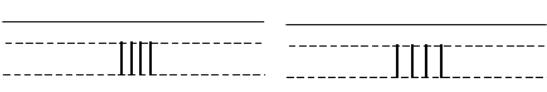
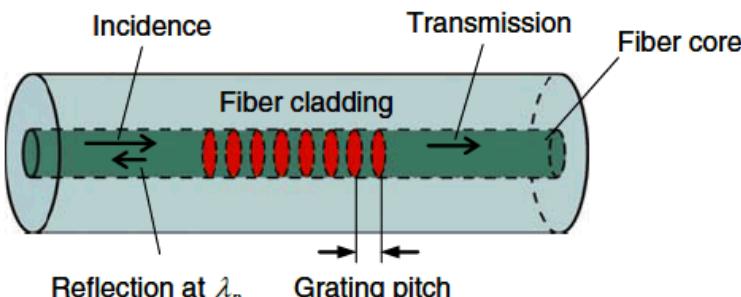
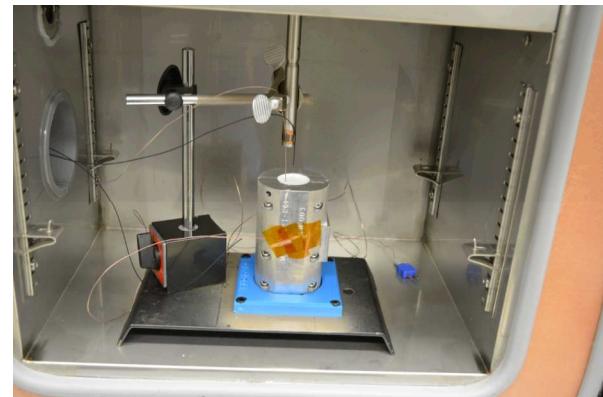
Epoxy Resins and their Stresses

- Two systems of epoxies
 - Epon 828 (diglycidyl ether of bisphenol A) cured with diethylamine (DEA) and filled with glass microballoons
 - Epon 826 cured with DEA and filled with carboxy-terminated butadiene nitrile (CTBN)
- Strain sources:
 - Post-gelation cure shrinkage
 - Thermal expansion mismatch
 - Shear stress at embedded geometry
- As epoxy cures its modulus evolves and viscoelastic response to strains changes
 - Modulus evolution will be tied to time and temperature of cure profile
- **By controlling the cure profile, we can reduce the stresses in the encapsulation system**

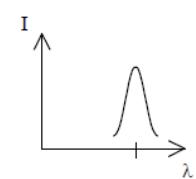


Fiber Bragg Grating Sensors

- Fiber Optic Bragg Grating Sensor (FBG)
- Allows for embedded measurements of strain in epoxy as it cures
- Can be removed from the mold
- Can be tested with real geometry

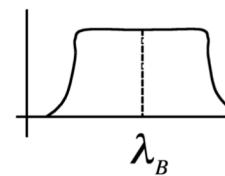


Reflected peak at lower center wavelength



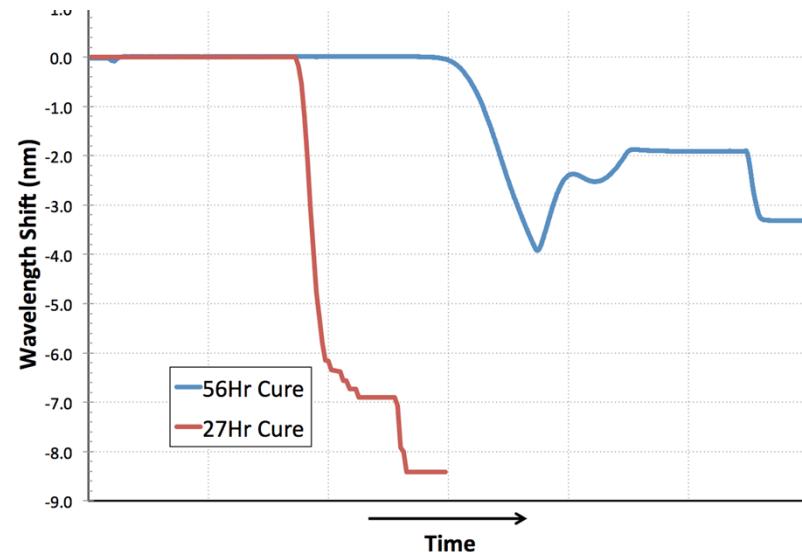
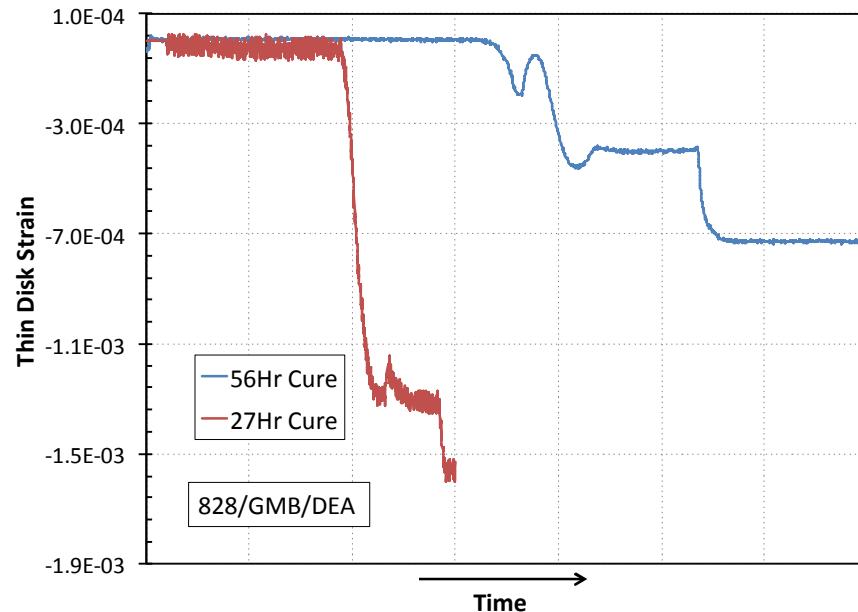
Reflected peak at higher center wavelength

Broad band reflection



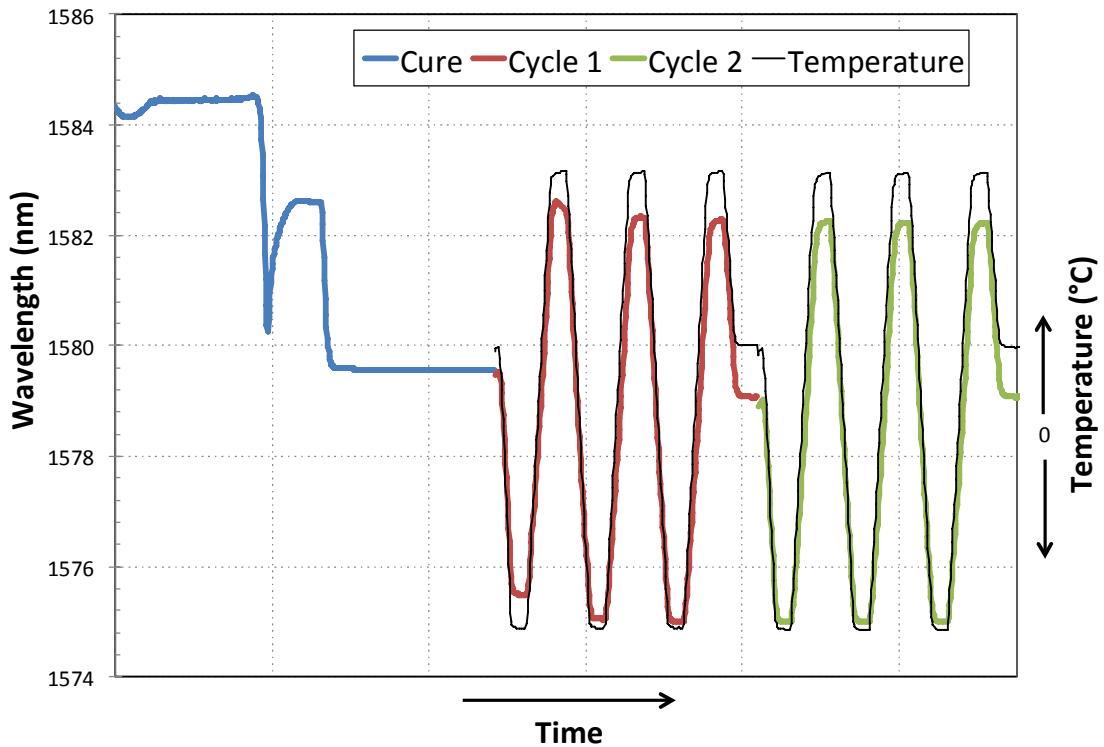
Simplified and Constrained Geometry Tests

- Pop-off tube geometry consists of Aluminum cylinder with thin disk at bottom
 - Allows for strains in epoxy to be measured with strain gauge as well as fiber optic sensor
 - Strain gauge mounted to thin disk that will flex as the epoxy shrinks during cure
 - Fiber optic sensor mounted vertically through center of cylinder
 - Sides of cylinder are sand-blasted to promote adhesion and constrain epoxy
- Analyzed two different non-isothermal cure profiles (27hr and 56hr)
 - 27hr cure had higher initial hold temperature than the 56hr allowing for faster reaction
 - Both cures had similar post-gelation ramp rate, max temperature, hold time, and cool-rate



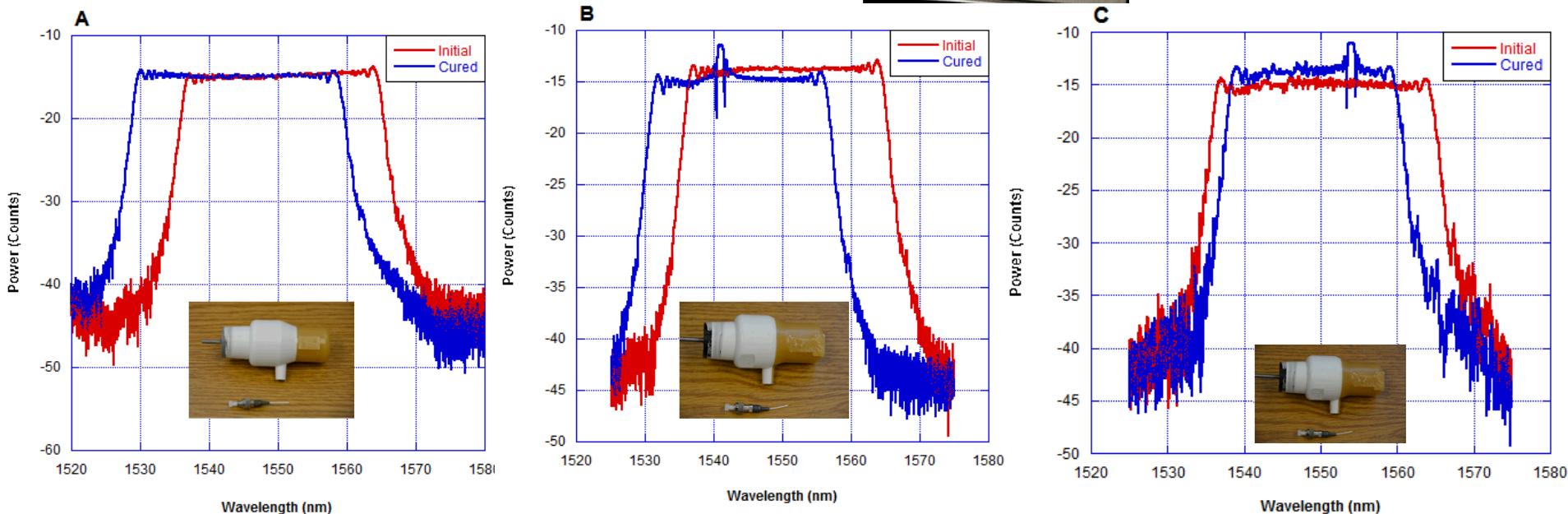
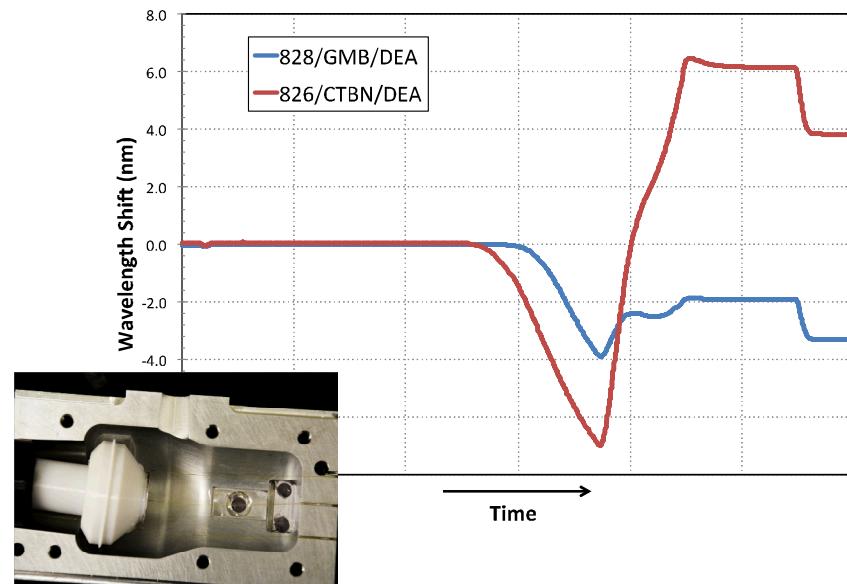
Production Mold

- Analyzed stresses in production mold through both cure and thermal cycling
- Stresses develop during cure from interaction between component and mold
 - Epoxy not able to fully relax
 - Increased stress at colder temperatures
- After first heating near T_g epoxy undergoes volume relaxation
 - Translates to fiber as compression
 - Continued cycling does not show added compression



Interacting with Internal Components and different Epoxy Systems

- Added an internal component as well as multiple epoxy systems as seen in real component
- Chirped fiber enables identification of interface layer
- Identified that decreasing strain in one epoxy system may lead to adverse impact from other epoxy system



Discussion

- Fiber optic Bragg Grating sensors offer unique method to understanding stress development in epoxy systems
- Powerful tool enabling variety of new experiments
 - In situ information on stress in real geometries at various locations
 - Understanding of stresses near epoxy interfaces in binary systems
- Continuing to develop modeling tools to help with data interpretation
 - Working to better understand epoxy reaction kinetics and how it relates to the production of stresses

Acknowledgements

- Roger Rasberry
- Pam Dellinger
- Garth D. Rohr
- Eric Udd (Columbia Gorge Research, LLC)
- Shawn Dirk



Thank you for attending!

System Details

- Fiber optic system:
 - Micron Optics sm125-500 (4-Ch, 80nm wavelength range, 2Hz scan rate)
 - Micron Optics si225-500 (8-Ch, 160nm wavelength range, 1kHz scan rate)
- Sensors:
 - Micron Optics os1100 FBG
 - Timbercon Inc and O/E Land Inc. custom-made 10mm chirped fibers